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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	80C51
Core Size	8-Bit
Speed	40MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	1.25K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89c51ac2-slsum

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

A/T89C51AC2



READ PIN -

Note: Port 2 p1 assists the logic-one output for memory bus cycles.



External Space

Memory Interface

The external memory interface comprises the external bus (port 0 and port 2) as well as the bus control signals (\overline{RD} , \overline{WR} , and ALE).

Figure 13 shows the structure of the external address bus. P0 carries address A7:0 while P2 carries address A15:8. Data D7:0 is multiplexed with A7:0 on P0. Table 17 describes the external memory interface signals.





Table 17.	External Data Memory	Interface Signals
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Signal Name	Туре	Description	Alternative Function
A15:8	0	Address Lines Upper address lines for the external bus.	P2.7:0
AD7:0	I/O	Address/Data Lines Multiplexed lower address lines and data for the external memory.	P0.7:0
ALE	0	Address Latch Enable ALE signals indicates that valid address information are available on lines AD7:0.	-
RD	0	Read Read signal output to external data memory.	P3.7
WR	0	Write Write signal output to external memory.	P3.6

External Bus Cycles

This section describes the bus cycles the A/T89C51AC2 executes to read (see Figure 14), and write data (see Figure 15) in the external data memory.

External memory cycle takes 6 CPU clock periods. This is equivalent to 12 oscillator clock period in standard mode or 6 oscillator clock periods in X2 mode. For further information on X2 mode.

Slow peripherals can be accessed by stretching the read and write cycles. This is done using the M0 bit in AUXR register. Setting this bit changes the width of the RD and WR signals from 3 to 15 CPU clock periods.

For simplicity, the accompanying figures depict the bus cycle waveforms in idealized form and do not provide precise timing information. For bus cycle timing parameters refer to the Section "AC Characteristics".



EEPROM Data Memory	The 2 KB on-chip EEPROM memory block is located at addresses 0000h to 07FFh of the XRAM/XRAM memory space and is selected by setting control bits in the EECON register. A read in the EEPBOM memory is done with a MOVX instruction.				
	A physical write in the EEPROM memory is done in two steps: write data in the column latches and transfer of all data latches into an EEPROM memory row (programming).				
	The number of data written on the page may vary from 1 up to 128 Bytes (the page size). When programming, only the data written in the column latch is programmed and a ninth bit is used to obtain this feature. This provides the capability to program the whole memory by Bytes, by page or by a number of Bytes in a page. Indeed, each ninth bit is set when the writing the corresponding byte in a row and all these ninth bits are reset after the writing of the complete EEPROM row.				
Write Data in the Column Latches	Data is written by byte to the column latches as for an external RAM memory. Out of the 11 address bits of the data pointer, the 4 MSBs are used for page selection (row) and 7 are used for byte selection. Between two EEPROM programming sessions, all the addresses in the column latches must stay on the same page, meaning that the 4 MSB must no be changed.				
	 The following procedure is used to write to the column latches: Save and disable interrupt. Set bit EEE of EECON register 				
	Load DPTR with the address to write				
	Store A register with the data to be written				
	Execute a MOVX @DPTR_A				
	 If needed loop the three last instructions until the end of a 128 Bytes page 				
	Restore interrupt				
	Note: The last page address used when loading the column latch is the one used to select the page programming address.				
Programming	The EEPPOM programming consists of the following actions:				
Frogramming	 writing one or more Bytes of one page in the column latches. Normally, all Bytes must belong to the same page; if not, the last page address will be latched and the others discarded. 				
	 launching programming by writing the control sequence (50h followed by A0h) to the EECON register. 				
	• EEBUSY flag in EECON is then set by hardware to indicate that programming is in progress and that the EEPROM segment is not available for reading.				
	The end of programming is indicated by a hardware clear of the EEBUSY flag.				
	Note: The sequence 5xh and Axh must be executed without instructions between then other- wise the programming is aborted.				
Read Data	The following procedure is used to read the data stored in the EEPROM memory:				
	Save and disable interrupt Save bit EEE of EECON register				
	• Execute a MOVX A, @DPTK				
	Restore Interrupt				

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FM0 Memory Architecture	 The Flash memory is made up of 4 blocks (see Figure 20): The memory array (user space) 32 KB The Extra Row The Hardware security bits The column latch registers
User Space	This space is composed of a 32 KB Flash memory organized in 256 pages of 128 Bytes. It contains the user's application code.
Extra Row (XRow)	This row is a part of FM0 and has a size of 128 Bytes. The extra row may contain infor- mation for boot loader usage.
Hardware Security Byte	The Hardware security Byte space is a part of FM0 and has a size of 1 byte. The 4 MSB can be read/written by software, the 4 LSB can only be read by software and written by hardware in parallel mode.
Column Latches	The column latches, also part of FM0, have a size of full page (128 Bytes). The column latches are the entrance buffers of the three previous memory locations (user array, XROW and Hardware security byte).
Cross Flash Memory Access Description	The FM0 memory can be program only from FM1. Programming FM0 from FM0 or from external memory is impossible.
	The FM1 memory can be program only by parallel programming.

The Table 23 show all software Flash access allowed.

		Action	FM0 (user Flash)	FM1 (boot Flash)
		Read	ok	-
E	FMO	Load column latch	ok	-
ig fro	(user Flash)	Write	-	-
cutin		Read	ok	ok
exe	FM1	Load column latch	ok	-
Code	(boot Flash)	Write	ok	-
		Read	-	-
	External memory	Load column latch	-	-
	EA = 0	Write	-	-

 Table 23.
 Cross Flash Memory Access





Note: The last page address used when loading the column latch is the one used to select the page programming address.

Programming the Flash Spaces

User

The following procedure is used to program the User space and is summarized in Figure 22:

- Load up to one page of data in the column latches from address 0000h to 7FFFh.
- Save then disable the interrupts.
- Launch the programming by writing the data sequence 50h followed by A0h in FCON register (only from FM1).
- The end of the programming indicated by the FBUSY flag cleared.
- Restore the interrupts.

Extra Row

The following procedure is used to program the Extra Row space and is summarized in Figure 22:

- Load data in the column latches from address FF80h to FFFFh.
- Save then disable the interrupts.
- Launch the programming by writing the data sequence 52h followed by A2h in FCON register. This step of the procedure must be executed from FM1. The end of the programming indicated by the FBUSY flag cleared. The end of the programming indicated by the FBUSY flag cleared.
- Restore the interrupts.





Figure 22. Flash and Extra Row Programming Procedure



Hardware Security Byte

The following procedure is used to program the Hardware Security Byte space and is summarized in Figure 23:

- Set FPS and map Hardware byte (FCON = 0x0C)
- Save and disable the interrupts.
- Load DPTR at address 0000h.
- Load Accumulator register with the data to load.
- Execute the MOVX @DPTR, A instruction.
- Launch the programming by writing the data sequence 54h followed by A4h in FCON register. This step of the procedure must be executed from FM1. The end of the programming indicated by the FBUSY flag cleared. The end of the programming indicated by the FBusy flag cleared.
- Restore the interrupts.



Operation Cross Memory Access

Space addressable in read and write are:

- RAM
- ERAM (Expanded RAM access by movx)
- XRAM (eXternal RAM)
- EEPROM DATA
- FM0 (user flash)
- Hardware byte
- XROW
- Boot Flash
- Flash Column latch

The table below provide the different kind of memory which can be accessed from different code location.

Table 27. Cross Memory Access

	Action	RAM	XRAM ERAM	Boot FLASH	FM0	E ² Data	Hardware Byte	XROW
boot ELASH	Read			OK	OK	OK	ОК	-
DOULTEASIT	Write			-	OK ⁽¹⁾	OK ⁽¹⁾	OK ⁽¹⁾	OK ⁽¹⁾
EMO	Read			ОК	OK	ОК	ОК	-
FIVIO	Write			-	OK (idle)	OK ⁽¹⁾	-	ОК
External	Read			-	-	ОК	-	-
EA = 0 or Code Roll Over	Write			-	-	OK ⁽¹⁾	-	-

Note: 1. RWW: Read While Write

Given Address

Each device has an individual address that is specified in the SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed. To address a device by its individual address, the SADEN mask byte must be 1111 1111b.

For example:

SADDR0101 0110b SADEN1111 1100b Given0101 01XXb

Here is an example of how to use given addresses to address different slaves:

Slave A:SADDR1111 0001b
SADEN1111 1010b
Given1111 0X0Xb
Slave B:SADDR1111 0011b SADEN1111 1001b
Given1111 0XX1b
Slave C:SADDR1111 0011b
SADENIIII IIUID
Given1111 00X1b

The SADEN byte is selected so that each slave may be addressed separately.

For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. 1111 0000b).

For slave A, bit 1 is a 0; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves A and B, but not slave C, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

Broadcast Address A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

SADDR 0101 0110b SADEN 1111 1100b SADDR OR SADEN1111 111Xb

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:SADDR1111 0001b

<u>SADEN1111 1010b</u>

Given1111 1X11b,

Slave B:SADDR1111 0011b

<u>SADEN1111 1001b</u>

Given1111 1X11B,

Slave C:SADDR=1111 0010b

<u>SADEN1111 1101b</u>

Given1111 1111b
```





Mode 0 (13-bit Timer)

Mode 0 configures Timer 0 as an 13-bit Timer which is set up as an 8-bit Timer (TH0 register) with a modulo 32 prescaler implemented with the lower five bits of TL0 register (see Figure 31). The upper three bits of TL0 register are indeterminate and should be ignored. Prescaler overflow increments TH0 register.

Figure 31. Timer/Counter x (x = 0 or 1) in Mode 0



Mode 1 (16-bit Timer)

Mode 1 configures Timer 0 as a 16-bit Timer with TH0 and TL0 registers connected in cascade (see Figure 32). The selected input increments TL0 register.

Figure 32. Timer/Counter x (x = 0 or 1) in Mode 1 See the "Clock" section



Table 44. TL1 Register

TL1 (S:8Bh) Timer 1 Low Byte Register

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-
Bit Number	Bit Mnemonic	Description					
7:0		Low Byte of	Timer 1.				

Reset Value = 0000 0000b



Programmable Clock-Output

In clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 37). The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency depending on the system oscillator frequency and the value in the RCAP2H and RCAP2L registers:

 $Clock - OutFrequency = \frac{FT2clock}{4 \times (65536 - RCAP2H/RCAP2L)}$

For a 16 MHz system clock in x1 mode, timer 2 has a programmable frequency range of 61 Hz ($F_{OSC}/2^{16}$) to 4 MHz ($F_{OSC}/4$). The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/T2 bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or different depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.









Registers

Table 45. T2CON Register

T2CON (S:C8h) Timer 2 Control Register

7	6	5	4	3	2	1	0		
TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2#	CP/RL2#		
Bit Number	Bit Mnemonic	Description							
7	TF2	Timer 2 Overflow Flag TF2 is not set if RCLK=1 or TCLK = 1. Must be cleared by software. Set by hardware on timer 2 overflow.							
6	EXF2	Timer 2 Externation Set when a contract of EXEN2=1. Set to cause is enabled. Must be clear	Timer 2 External Flag Set when a capture or a reload is caused by a negative transition on T2EX pin if EXEN2=1. Set to cause the CPU to vector to timer 2 interrupt routine when timer 2 interrupt s enabled. Must be cleared by software.						
5	RCLK	Receive Clo Clear to use Set to use tir	Receive Clock bit Clear to use timer 1 overflow as receive clock for serial port in mode 1 or 3. Set to use timer 2 overflow as receive clock for serial port in mode 1 or 3.						
4	TCLK	Transmit Cle Clear to use Set to use tir	Transmit Clock bit Clear to use timer 1 overflow as transmit clock for serial port in mode 1 or 3. Set to use timer 2 overflow as transmit clock for serial port in mode 1 or 3.						
3	EXEN2	Timer 2 Exte Clear to igno Set to cause detected, if ti	Timer 2 External Enable bit Clear to ignore events on T2EX pin for timer 2 operation. Set to cause a capture or reload when a negative transition on T2EX pin is detected, if timer 2 is not used to clock the serial port.						
2	TR2	Timer 2 Run Clear to turn Set to turn of	Timer 2 Run Control bit Clear to turn off timer 2. Set to turn on timer 2.						
1	C/T2#	Timer/Coun Clear for time Set for count	Timer/Counter 2 Select bit Clear for timer operation (input from internal clock system: F _{OSC}). Set for counter operation (input from T2 input pin).						
0	CP/RL2#	Timer 2 Cap If RCLK=1 of timer 2 overf Clear to auto EXEN2=1. Set to captur	Timer 2 Capture/Reload bit If RCLK=1 or TCLK=1, CP/RL2# is ignored and timer is forced to auto-reload on timer 2 overflow. Clear to auto-reload on timer 2 overflows or negative transitions on T2EX pin if EXEN2=1. Set to capture on negative transitions on T2EX pin if EXEN2=1.						

Reset Value = 0000 0000b Bit addressable



Table 48. TL2 Register

TL2 (S:CCh) Timer 2 Low Byte Register

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-
Bit Number	Bit Mnemonic	Description					
7-0		Low Byte of	Timer 2.				

Reset Value = 0000 0000b Not bit addressable

Table 49. RCAP2H Register

RCAP2H (S:CBh) Timer 2 Reload/Capture High Byte Register

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-
Bit Number	Bit Mnemonic	Description					
7-0		High Byte of Timer 2 Reload/Capture.					

Reset Value = 0000 0000b Not bit addressable

Table 50. RCAP2L Register

RCAP2L (S:CAH) TIMER 2 Reload/Capture Low Byte Register

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-
Bit Number	Bit Mnemonic	Description					
7-0		Low Byte of	Timer 2 Reloa	d/Capture.			

Reset Value = 0000 0000b Not bit addressable



Watchdog Programming

The three lower bits (S0, S1, S2) located into WDTPRG register permit to program the WDT duration.

Table 51. Machine Cycle Count

S2	S1	S0	Machine Cycle Count
0	0	0	2 ¹⁴ - 1
0	0	1	2 ¹⁵ - 1
0	1	0	2 ¹⁶ - 1
0	1	1	2 ¹⁷ - 1
1	0	0	2 ¹⁸ - 1
1	0	1	2 ¹⁹ - 1
1	1	0	2 ²⁰ - 1
1	1	1	2 ²¹ - 1

To compute WD Time-Out, the following formula is applied:

$$FTime - Out = \frac{F_{osc}}{6 \times 2^{WDX2 \wedge X2} (2^{14} \times 2^{Svalue})}$$

Note: Svalue represents the decimal value of (S2 S1 S0)

The following table outlines the time-out value for $\mathsf{Fosc}_{\mathsf{XTAL}}$ = 12 MHz in X1 mode

S2	S1	S0	Fosc = 12 MHz	Fosc = 16 MHz	Fosc = 20 MHz
0	0	0	16.38 ms	12.28 ms	9.82 ms
0	0	1	32.77 ms	24.57 ms	19.66 ms
0	1	0	65.54 ms	49.14 ms	39.32 ms
0	1	1	131.07 ms	98.28 ms	78.64 ms
1	0	0	262.14 ms	196.56 ms	157.28 ms
1	0	1	524.29 ms	393.12 ms	314.56 ms
1	1	0	1.05 s	786.24 ms	629.12 ms
1	1	1	2.10 s	1.57 s	1.25 s

Table 52. Time-Out Computation

Each module in the PCA has a special function register associated with it (CCAPM0 for module 0...). The CCAPM0:4 registers contain the bits that control the mode that each module will operate in.

- The ECCF bit enables the CCF flag in the CCON register to generate an interrupt when a match or compare occurs in the associated module.
- The PWM bit enables the pulse width modulation mode.
- The TOG bit when set causes the CEX output associated with the module to toggle when there is a match between the PCA counter and the module's capture/compare register.
- The match bit MAT when set will cause the CCFn bit in the CCON register to be set when there is a match between the PCA counter and the module's capture/compare register.
- The two bits CAPN and CAPP in CCAPMn register determine the edge that a capture input will be active on. The CAPN bit enables the negative edge, and the CAPP bit enables the positive edge. If both bits are set both edges will be enabled.
- The bit ECOM in CCAPM register when set enables the comparator function.

PCA Interrupt

Figure 40. PCA Interrupt System



PCA Capture Mode

To use one of the PCA modules in capture mode either one or both of the CCAPM bits CAPN and CAPP for that module must be set. The external CEX input for the module (on port 1) is sampled for a transition. When a valid transition occurs the PCA hardware loads the value of the PCA counter registers (CH and CL) into the module's capture registers (CCAPnL and CCAPnH). If the CCFn bit for the module in the CCON SFR and the ECCFn bit in the CCAPMn SFR are set then an interrupt will be generated.





Figure 41. PCA Capture Mode



16-bit Software Timer Mode

The PCA modules can be used as software timers by setting both the ECOM and MAT bits in the modules CCAPMn register. The PCA timer will be compared to the module's capture registers and when a match occurs an interrupt will occur if the CCFn (CCON SFR) and the ECCFn (CCAPMn SFR) bits for the module are both set.

Figure 42. PCA 16-bit Software Timer and High Speed Output Mode





Table 71. IEN1 Register

IEN1 (S:E8h) Interrupt Enable Register

7	6	5	4	3	2	1	0			
-	-	-	-	-	-	EADC	-			
Bit Number	Bit Mnemonic	Description	Description							
7	-	Reserved The value re	ad from this b	it is indetermi	nate. Do not s	et this bit.				
6	-	Reserved The value re	ad from this b	it is indetermi	nate. Do not s	et this bit.				
5	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.							
4	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.							
3	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.							
2	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.							
1	EADC	ADC Interru Clear to disa Set to enable	ADC Interrupt Enable bit Clear to disable the ADC interrupt. Set to enable the ADC interrupt.							
0	-	Reserved The value read from this bit is indeterminate. Do not set this bit.								

Reset Value = xxxx xx00b bit addressable

Table 72. IPL0 Register

IPL0 (S:B8h) Interrupt Enable Register

7	6	5	4	3	2	1	0		
-	PPC	PT2	PS	PT1	PX1	PT0	PX0		
Bit Number	Bit Mnemonic	Description	Description						
7	-	Reserved The value re	ad from this b	it is indetermir	nate. Do not s	et this bit.			
6	PPC	PCA Interru Refer to PPC	pt Priority bi CH for priority	t level					
5	PT2	Timer 2 Ove Refer to PT2	Timer 2 Overflow Interrupt Priority bit Refer to PT2H for priority level.						
4	PS	Serial Port F Refer to PSF	Serial Port Priority bit Refer to PSH for priority level.						
3	PT1	Timer 1 Ove Refer to PT1	Timer 1 Overflow Interrupt Priority bit Refer to PT1H for priority level.						
2	PX1	External Interrupt 1 Priority bit Refer to PX1H for priority level.							
1	PT0	Timer 0 Overflow Interrupt Priority bit Refer to PT0H for priority level.							
0	PX0	External Interrupt 0 Priority bit Refer to PX0H for priority level.							

Reset Value = X000 0000b bit addressable



Electrical Characteristics

Absolute Maximum Ratings*

Ambiant Temperature Under Bias:	*NOTICE:
I = industrial40°C to 85°C	
Storage Temperature65°C to + 150°C	
Voltage on V_{CC} from V_{SS} 0.5V to + 6V	
Voltage on Any Pin from V_{SS} -0.5V to V_{CC} + 0.2V	
Power Dissipation 1W	

DC Parameters for Standard Voltage

TA = -40°C to +85°C; V_{SS} = 0V; V_{CC} = 3V to 5.5V; F = 0 to 40 MHz

Stresses at or above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability. The power dissipation is based on the maximum allowable die temperature and the thermal resistance of the package.

Table 76.	DC Parameters in Standard Voltage					
Symbol	Parameter	Min	Typ ⁽⁵⁾	Мах	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2Vcc - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3 and $4^{(6)}$			0.3 0.45 1.0	> > >	$\begin{split} I_{OL} &= 100 \; \mu A^{(4)} \\ I_{OL} &= 1.6 \; m A^{(4)} \\ I_{OL} &= 3.5 \; m A^{(4)} \end{split}$
V _{OL1}	Output Low Voltage, port 0, ALE, PSEN ⁽⁶⁾			0.3 0.45 1.0	V V V	$\begin{split} I_{OL} &= 200 \; \mu A^{(4)} \\ I_{OL} &= 3.2 \; m A^{(4)} \\ I_{OL} &= 7.0 \; m A^{(4)} \end{split}$
V _{OH}	Output High Voltage, ports 1, 2, 3, 4 and 5	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			> > >	I _{OH} = -10 μA I _{OH} = -30 μA I _{OH} = -60 μA
V _{OH1}	Output High Voltage, port 0, ALE, PSEN	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	I _{OH} = -200 μA I _{OH} = -3.2 mA I _{OH} = -7.0 mA
R _{RST}	RST Pulldown Resistor	20	40	200	kΩ	
I _{IL}	Logical 0 Input Current ports 1, 2, 3 and 4			-50	μA	Vin = 0.45V
ILI	Input Leakage Current			±10	μA	0.45V < Vin < V _{CC}
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3 and 4			-650	μA	Vin = 2.0V
C _{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I _{PD}	Power-down Current		160	350	μA	$3V < V_{CC} < 5.5V^{(3)}$
I _{cc}	Power Supply Current	$I_{CCOP} = 0.7 \text{ Freq (MHz)} + 3 \text{ mA}$ $ICC_FLASH_WRITE^{(7)} = 0.4 \text{ Freq (MHz)} + 20 \text{ mA}$ $I_{CCIDLE} = 0.6 \text{ Freq (MHz)} + 2 \text{ mA}$				$3V < V_{CC} < 5.5V^{(1)(2)}$





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